221 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

225 ■ Tape Coil, RX into bottom of case, CENTERED, coil side down, lead wires passing through milled groove.

226 ■ Install PCB in Case using #4 x 3/8 screws, inserting 0.1 thick spacers between PCB and case.

227 ■ The value of R2 + R6 can be adjusted to 250-ohms for WPC 1.1 requirements (F00 calibration only for this EVM).

222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Components marked 'DNP' should not be populated.

Assembly Variant: 001

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<th>PCB Viewed From Top Side</th>
<th>Board #: PWR731</th>
<th>Rev: A</th>
<th>Sun Rev: Not In VersionControl</th>
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Plot Name = Top Assembly Drawing

Generated: 7/21/2015 4:46:42 PM  Texas Instruments
**COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.**
**ASSEMBLY VARIANT: 001**

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